



Real Systems. Real Traction.

Bringing High-Performance RISC-V Platforms to Life

Balaji Baktha, CEO, Ventana Micro Systems

RISC-V Europe Summit, Paris 2025

VENTANA Delivers a Full-Scale Compute Platform

Frictionless - Making it easy for customers to adopt RISC-V in their data center applications



SOFTWARE STACK



SYSTEM IP



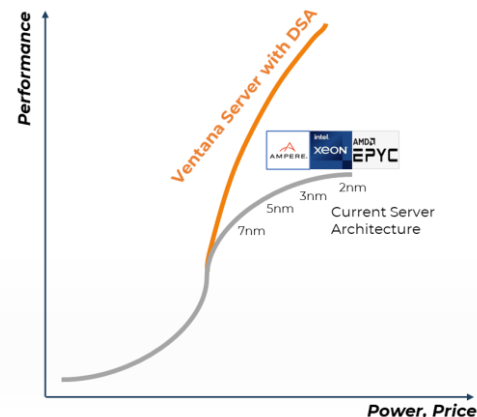
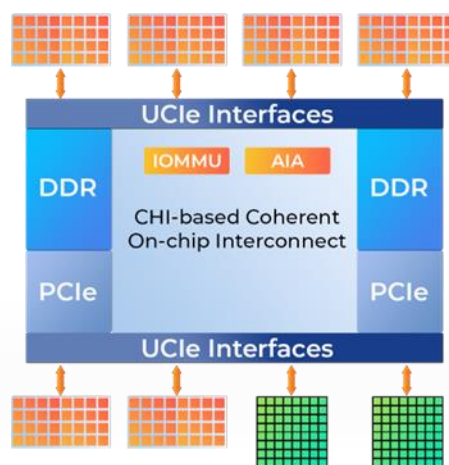
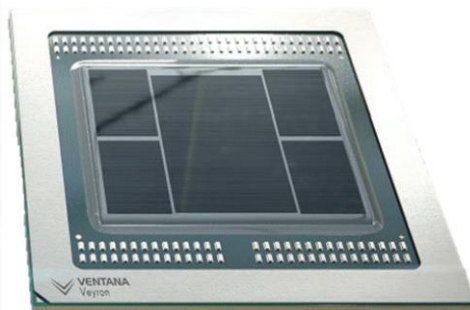
GENERATIVE AI



DOMAIN SPECIFIC
ACCELERATION



CHIPLET
TECHNOLOGY



SECURITY



RAS



LOW LATENCY
COHERENT NOC



HIGH PERFORMANCE
CACHE ARCHITECTURE



HIGH PERFORMANCE
CPU

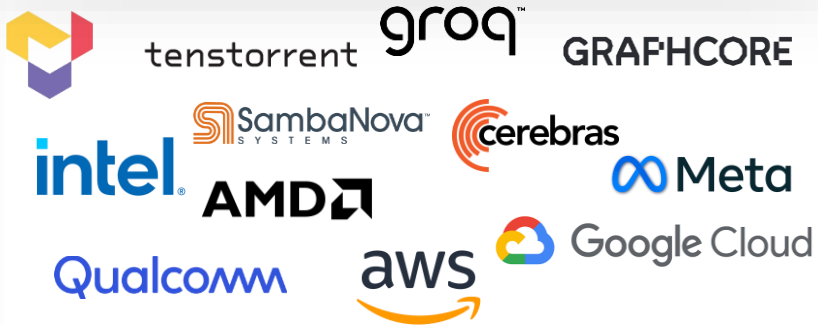


FEATURE PARITY
WITH LEADING CPU
ARCHITECTURES



AI Acceleration is Fragmented – RISC-V Unifies It

They All Struggle Because



- ⊘ **Fragmented Architectures**
- ⊘ **Reinvented Software Stacks**
- ⊘ **No Shared Investment →**
No CUDA Alternative

AI Workloads Vary Compute Must Scale

Training

Attached Matrix

Integrated Matrix

Vector/Dot Product

Signal Processing/
Classical ML

**But They All need a
Unified Foundation**

RISC-V Enables Ecosystem Scale

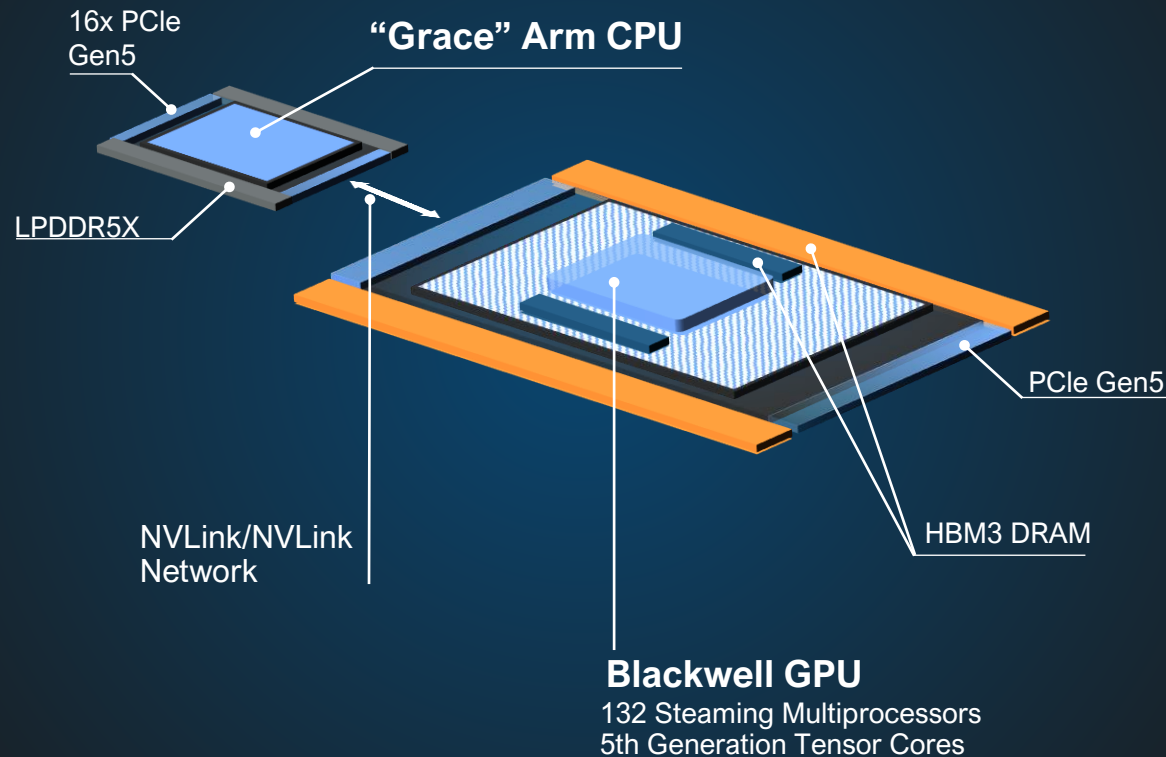


- ✓ **Share ISA across CPUs and accelerators**
- ✓ **Scalable to fit across any AI Tier**
- ✓ **Common toolchain and compiler infrastructure**
- ✓ **Ecosystem leverage as industry wide scale**

Different Workloads need different compute.
But they all need a unified foundation.

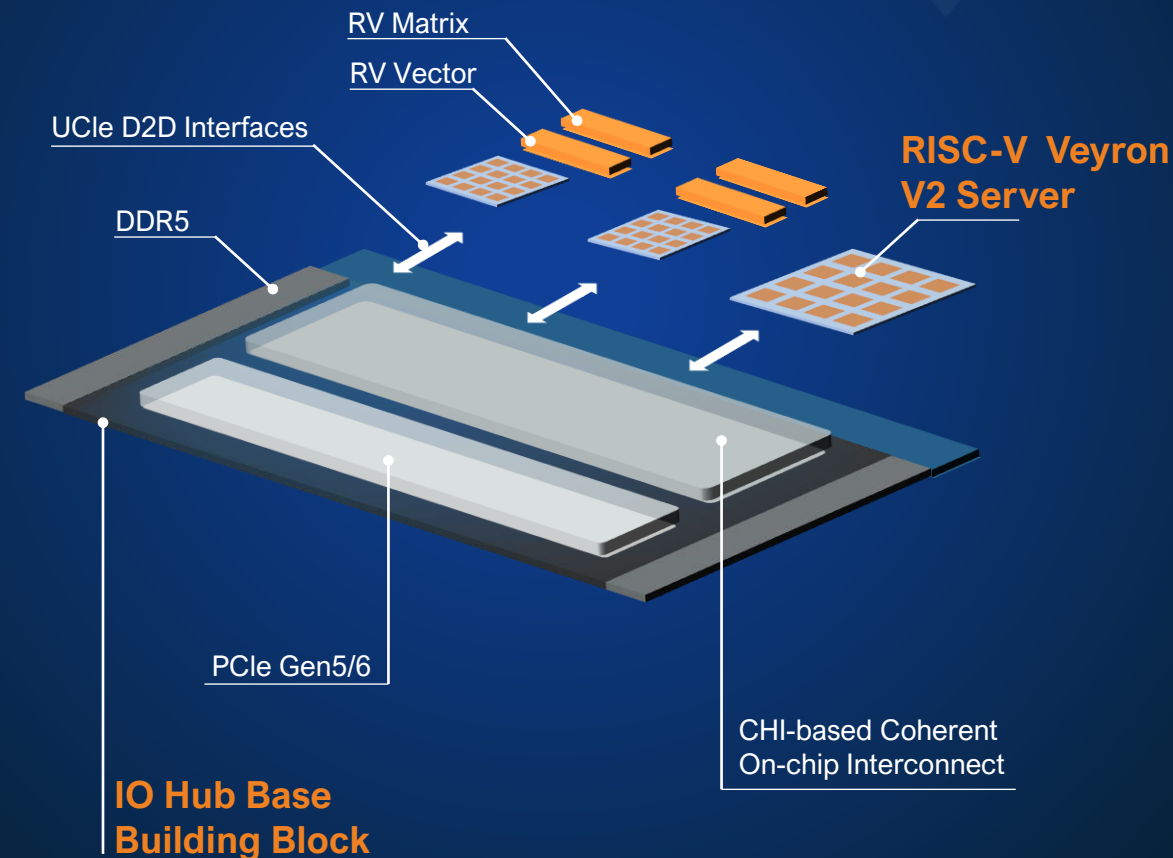
From Grace Blackwell to Open Compute: Ventana Enables the RISC-V AI Superchip

RISC-V Equivalents to Nvidia Grace Blackwell



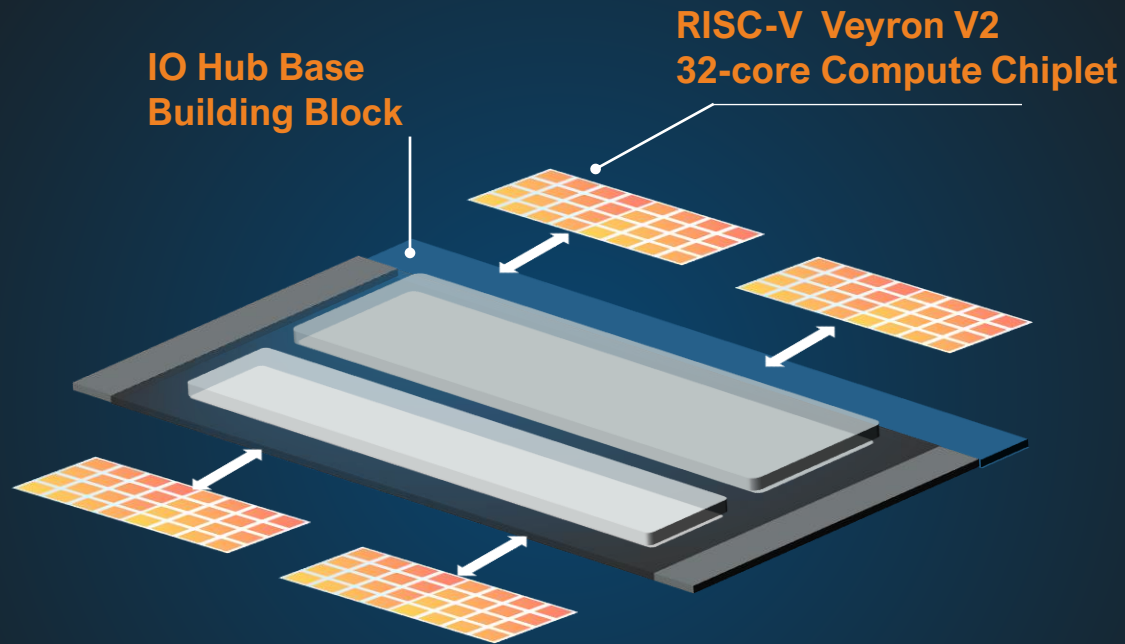
CPU+AI Equivalent Using Ventana RISC-V

RISC-V Based Veyron E2 "RUCA" Chiplets



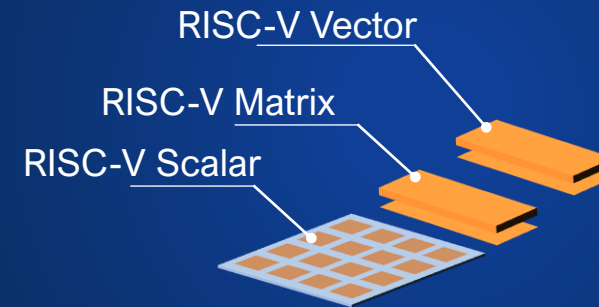
Turning Vision into Action: Real-World Execution from Compute to AI

Cloud Compute Server Partners



AI Acceleration Partners

Veyron E2-based “RUCA” AI/HPC Acceleration



Ventana is the only company delivering both RISC-V compute and RISC-V AI Acceleration – in real silicon, at system scale with a high-performance platform ready for the data center

The Big Announcement!

High Efficiency, Scale-Out Processors

- 7 SPECint2017 rate=1, up to 3.2GHz
- Chiplet: 32-core, 128MB L3, 70W TDP
- RVA23 profile compliant
- RVV vector + custom AI/ML matrix
- UCle D2D with AMBA CHI transport
- Portable design, standard library and memory compiler, standard PD flow
- TSMC N4

Veyron V2 (N4)

- 8.4 SPECint2017 rate=1, up to 3.85GHz
- Chiplet: 32-core, 128MB L3
- RVA23 profile compliant
- RVV vector + custom AI/ML matrix
- UCle D2D with AMBA CHI transport
- Frequency push with semi-custom arrays and select custom cells/macros
- TSMC N3

Veyron V2 (N3)

- 11+ SPECint2017 rate=1, up to 4.2GHz
- Chiplet: 32-core, 128MB L3
- Post-RVA23 extension updates
- RISC-V standard AI/ML matrix extensions
- Integrated scalar/vector/matrix compute
- Large IPC and Perf/W gains
- UCle D2D, optional 3D stacking and direct memory attach

Veyron V3

Builds on established V2 performance

Roadmap to V3

Unlike others, Ventana uses absolute SPECint2017 results, not Spec/GHz modeling.
No extrapolations. No outdated 2006 benchmarks. Just real performance.

Veyron V3 Goals and Targets

- **High Single-Thread Performance with High Power Efficiency – Optimized for Scale-Out Datacenter Compute and Maximizing Single-Socket Performance**
 - 11+ SPECint2017 rate=1
 - 24 TeraFlops per core of AI/ML FP8 matrix compute (4.5+ PetaFlops in a single 192-core SiP)
 - High-bandwidth, low-latency coherent fabric enables excellent cluster performance scaling
- **Builds on Proven Veyron V2 Foundation**
 - Large IPC gains through combination of new uarch innovations and enhancements to existing uarch
 - Same base microarchitecture with the foundation already laid for V3 uarch innovations
- **Advanced Microarchitecture for Power & Performance**
 - Dense-compute internal macro-ops, advanced multi-instruction-to-macro-op fusion, caching of macro-op sequences
 - Software-transparent hardware optimization of warm and hot macro-op sequences
 - Atypical uarch choices to achieve both high performance and low power (e.g. virtual DL1 cache eliminates complex power-hungry and timing-critical multi-ported CAM-based L1 TLB)
- **High Frequency of Operation – up to 4.2 GHz**
 - Targeted semi-custom P&R flow for frequency optimization of critical structures
 - Targeted custom high-speed standard cells and SRAM macros
 - Benefits of advanced process node

V3 Microarchitecture Overview

- **Aggressive Out-of-Order design**
 - Superscalar, decouple fetch/predict front end
 - Large caches, BTB, resource queues, schedulers, ROB, etc.
- **Advanced Branch and Memory Prediction**
 - Multiple primary and secondary branch predictors
 - Memory dependence and bypass predictors, load value predictor, ...
- **High Parallelism**
 - 16 execution schedulers and pipelines
 - 5 integer, 3 load/store, 3 scalar FP, 5 vector/matrix
 - 200+ scheduler entries
- **Macro-Op Optimized Microarchitecture → Acts Much Wider Than It Looks**
 - Dense-compute macro-ops encode multiple RISC-V instructions
 - Macro-ops magnify effective decode width, sizes of backend queues and tracking structures, and number of schedulers and execution pipelines - without growing them physically
 - Optimizes performance while saving power and area
 - **Avoids costly brute-force 10-16 wide approaches to increasing IPC**

Macro-Ops, Advanced Fusion Engine, Macro-Op Cache

- **High Compute-Density Macro-Ops**

- Internal macro-ops encode 1-5 RISC-V instructions
- Load/store operations with complex address calculations and 4-cycle load-to-use
- Single-cycle execution for complex three-operand register and branch operations
- Reduces power per RISC-V instruction across the microarchitecture

- **Advanced Fusion Engine**

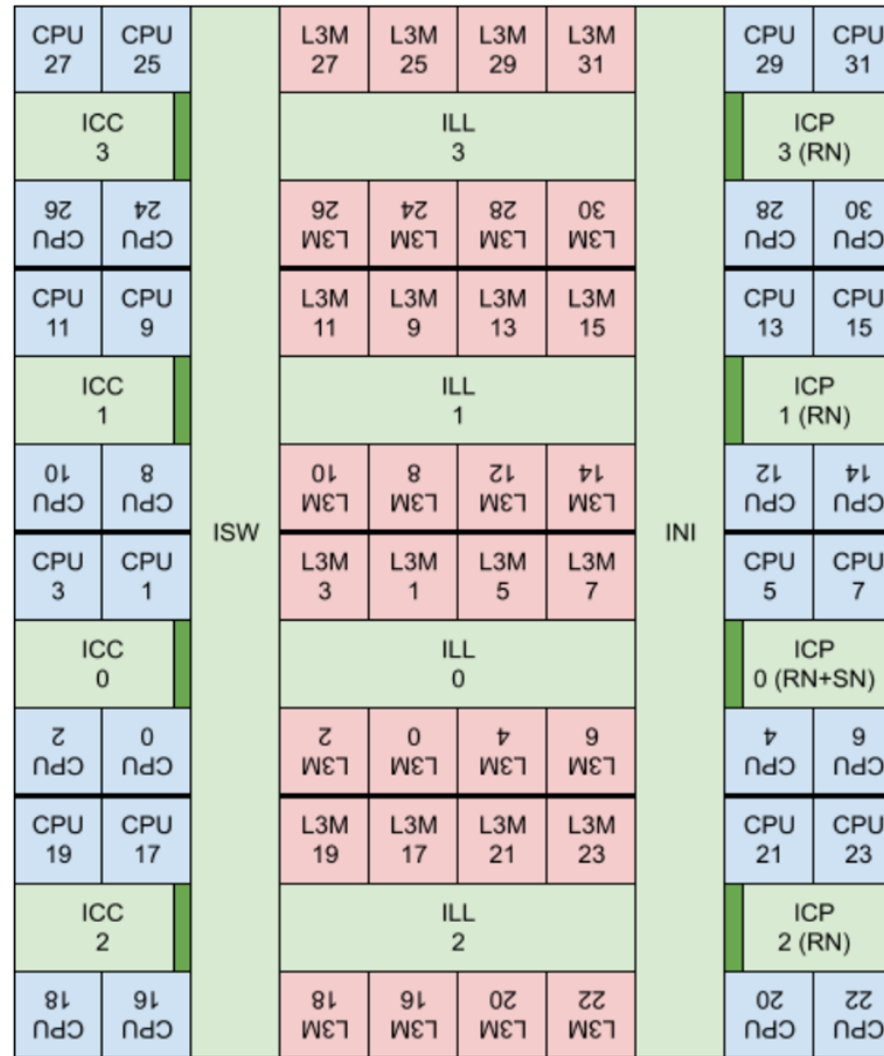
- Operates on warm and hot sections of RISC-V code
- Dynamically fuses multiple RISC-V instructions into optimized macro-ops
- Performs a variety of code optimizations that generally increase ILP and shorten code execution path lengths

- **"IL1" Macro-Op Cache**

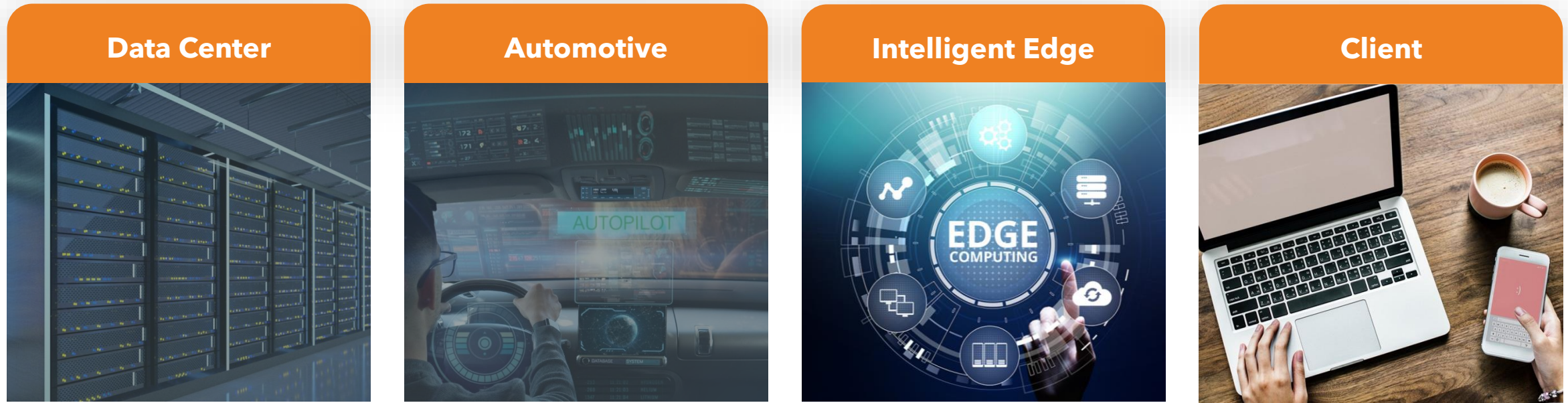
- Caches optimized variable-length macro-op sequences
- Bypasses fetch/decode and reduces power for most code execution
- Fully hardware-coherent and TLB-consistent (i.e. fully software transparent)

32-Core / 128 MB L3 Compute Cluster Topology

- 32 cores
- 32 L3 slices
- 2-D mesh interconnect modules
- Physically scalable topology
- Interconnect bandwidth and L3 bandwidth scales with core count
- Cluster to SoC bandwidth scales with core count



Scalable RISC-V Architecture for Every High-Performance Market



Unified Veyron Architecture: Scales from hyperscale compute to ultra-efficient edge and client form factors.

Power, Performance & Safety Flexibility: Data center-class throughput | Automotive-grade features including ASIL-B/D safety (ISO 26262) | Software test libraries | ECC/parity protection, fault isolation | Power-aware clusters for edge and mobile

Platform Coverage: Coherent compute + AI across segments | Shared toolchain, ISA, and optimization path | Production-ready platform delivery for Tier 1 & OEM alignment



- ✓ **Highest-Performance RISC-V CPUs—With Production Silicon on the Way**
- ✓ **Delivering Real High-Performance RISC-V Systems—Hardware, Software, and Platform**
- ✓ **Scalable AI Acceleration—Data Center to Client, Fully RISC-V**
- ✓ **Enabling Momentum Across the Ecosystem and Customer Designs**
- ✓ **Veyron V3 Extends Product Leadership**

